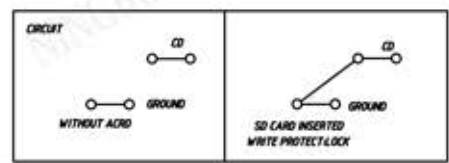
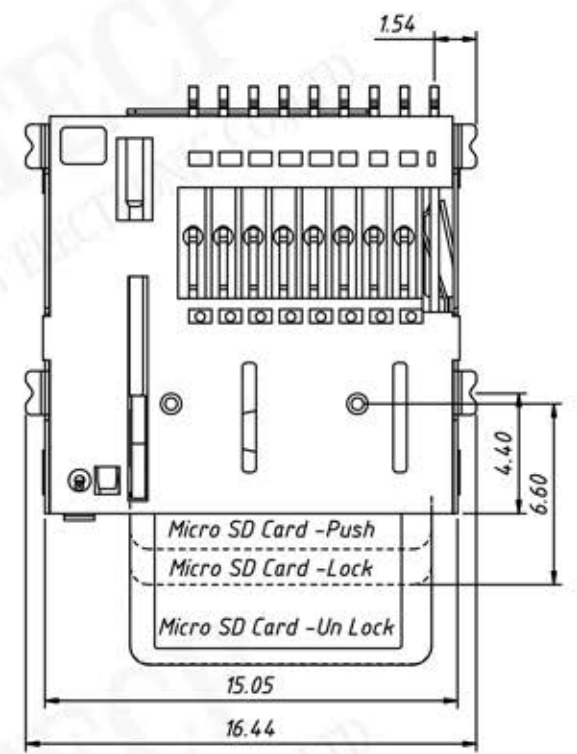
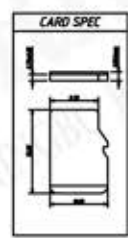
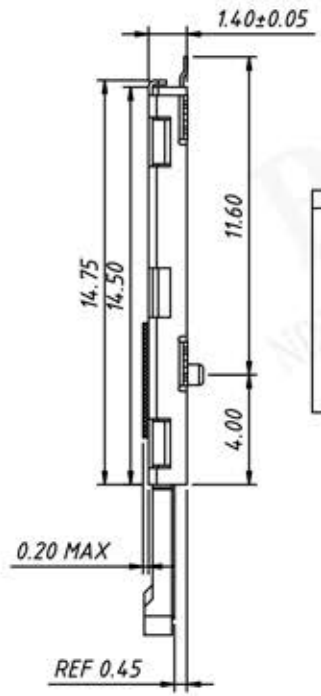
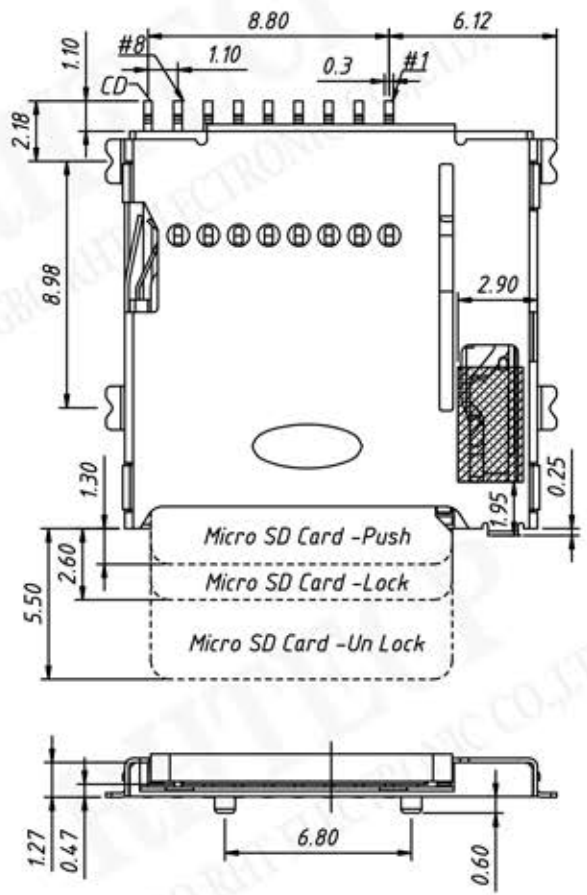
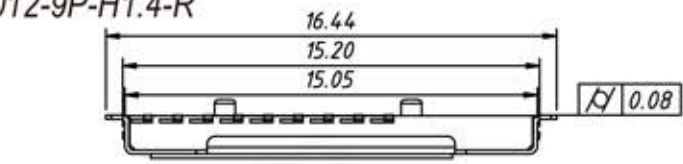
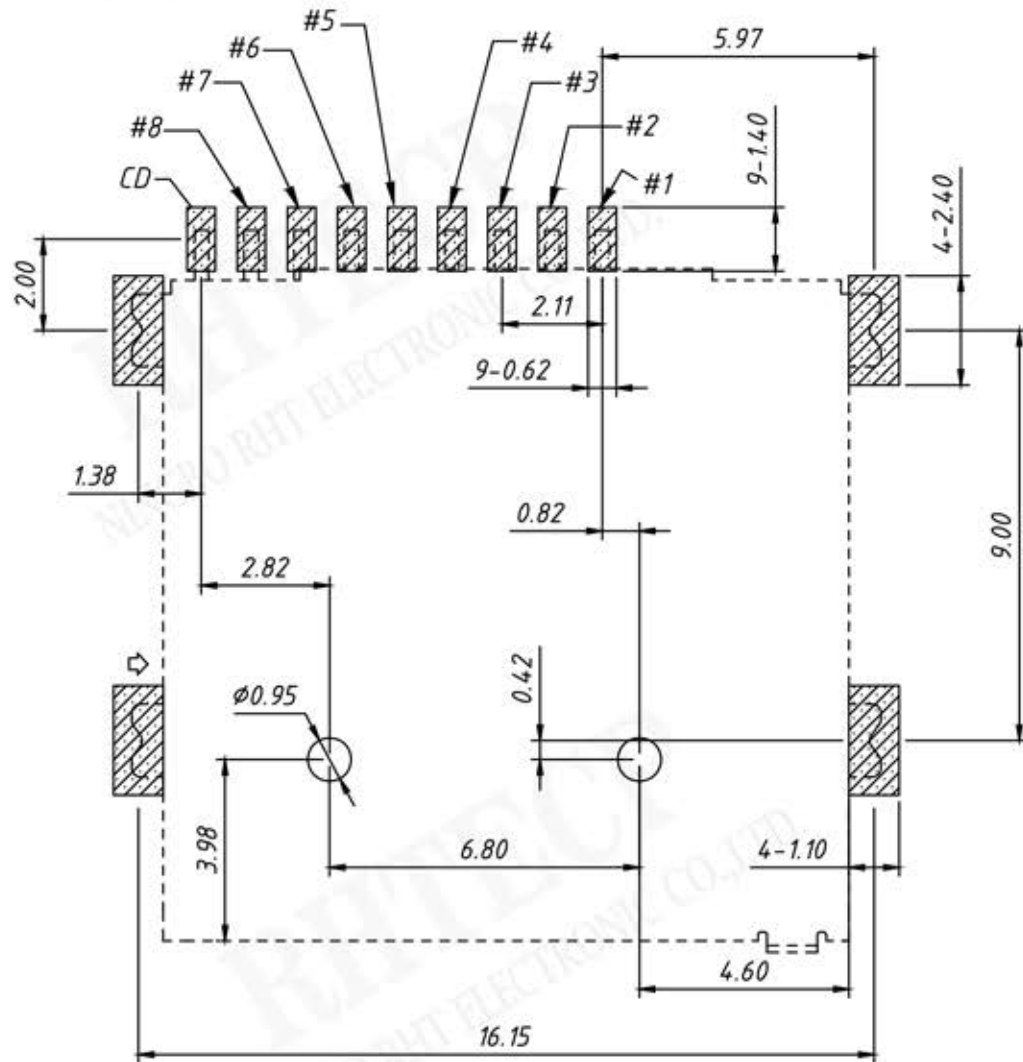


P/N: RE-C-TF-012-9P-H1.4-R



UNITS:mm	SHEET SIZE:A4		SCALE: ---
> 0 ~ 3	> 3 ~ 18	> 18 ~ 50	> 50 ~ 120
± 0.12	± 0.15	± 0.3	± 0.5

P/N:RE-C-TF-012-9P-H1.4-R



PCB AREA

RECOMMENDED PCB LAYOUT

CONTACT AREA

TOLERANCE ± 0.05

Material:

Insulator: High Temperature Thermoplastic, UL 94V-0.

Terminal: Copper Alloy, Plated 50u" Ni Overall. Plated Au Selective Contact Area Plated 100u" Sn Over Ni On Solder Area.

Shell: Plated 50u" Ni Overall. Plated Au Selective Contact Area

Electrical:

Current Rating: 0.5 A AC/DC max.

Voltage Rating: 125V AC/DC

Ambient Temperature Range: $-25^{\circ}\text{C} \sim +85^{\circ}\text{C}$

Storage Temperature Range: $-25^{\circ}\text{C} \sim +85^{\circ}\text{C}$

Ambient Humidity Range: 95% R.H. Max.

Contact Resistance: 100m Ω Max.

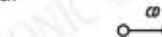
Insulation Resistance: 1000M Ω Min./500VDC

Mating Cycles: 5000-20000 Insertions.

Peak temperature: $260^{\circ}\text{C} \pm 0.5^{\circ}\text{C}$

PIN NO.	PIN ASSIGNMENT
1 #	DAT2
2 #	CD/DAT3
3 #	CMD
4 #	VDD
5 #	CLK
6 #	VSS
7 #	DAT0
8 #	DAT1
9 #	CD

CIRCUIT



WITHOUT ACID GROUND



SD CARD INSERTED
WRITE PROTECT LOCK